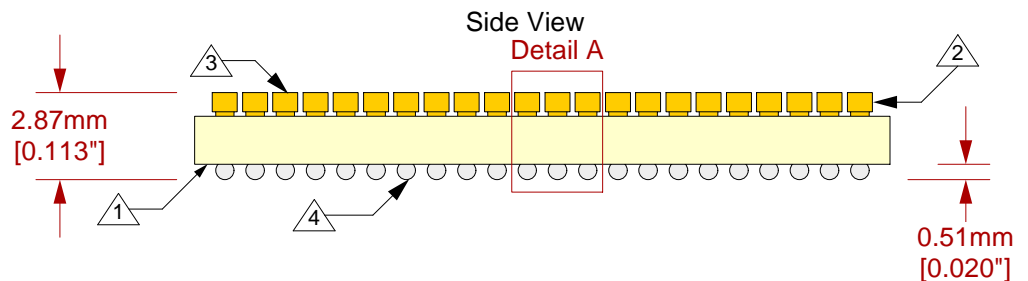
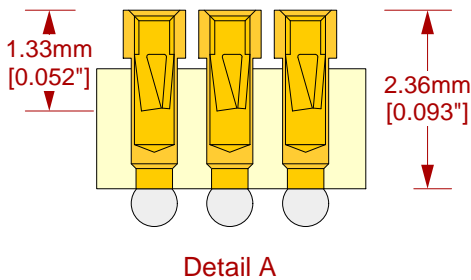
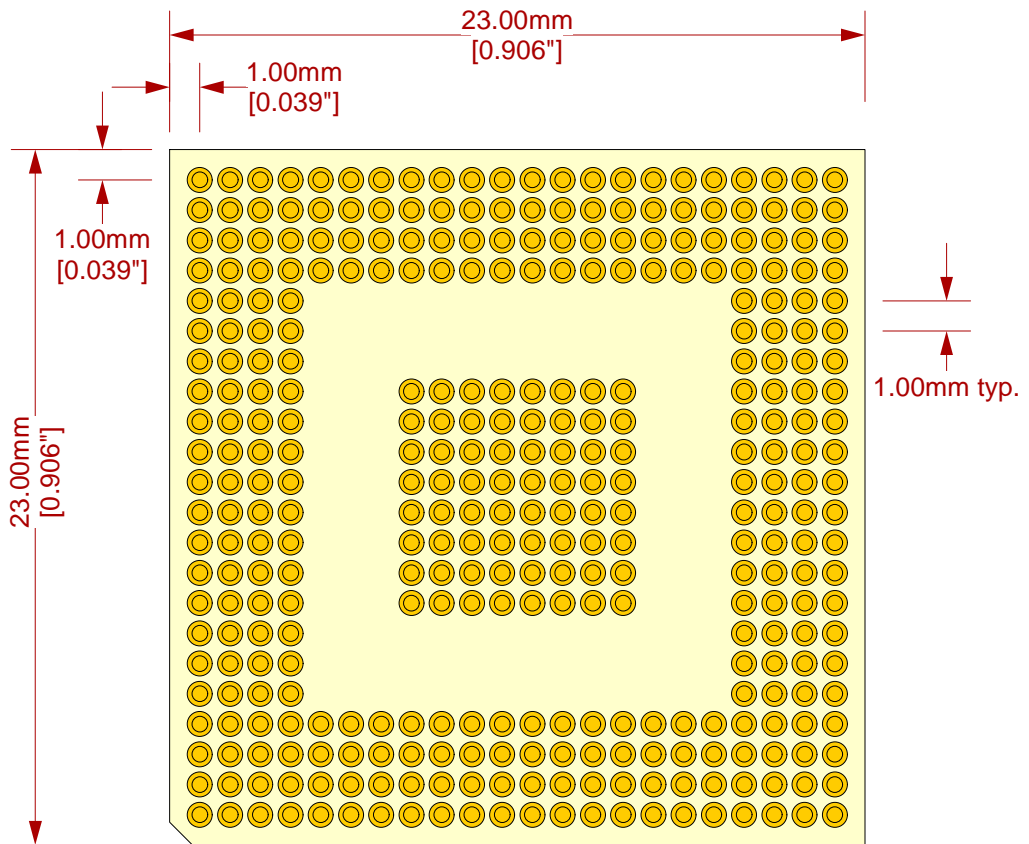


Ordering Information

Solder Ball Alloy	Part Number Suffix
Sn63Pb37	-62
Sn96.5Ag3.0Cu0.5	-62F*

\*RoHS Compliant



- ① Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. (RoHS)
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
- ③ Contacts: Beryllium Copper Alloy172, HT; Finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
- ④ Solder Balls: [See table above](#)

**CONTACT DATA**

Accepts 0.20mm - 0.33mm Diameter pins  
 3-finger  
 37/25 gram, Initial insertion force (with 0.254mm/0.203mm dia. pin)  
 30/22 gram, normal force (with 0.254mm/0.203mm dia. pin)  
 20/17 gram, extraction force (with 0.254mm/0.203mm dia. pin)

**Description:** Giga-snaP BGA SMT Foot

352 position (1.0mm pitch) gold plated female receptacle pins to SMT solder balls (BGA type). Pin assignment 1:1.

**Tolerances:** diameters ±0.03mm [±0.001"], PCB perimeters ±0.18mm [±0.007"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA352E-B-42F Drawing		Status: Released	Scale: 4:1	Rev: A
 © 2010 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: V. Panavala		Date: 10/8/10	
	File: SF-BGA352E-B-42F Dwg		Modified:	